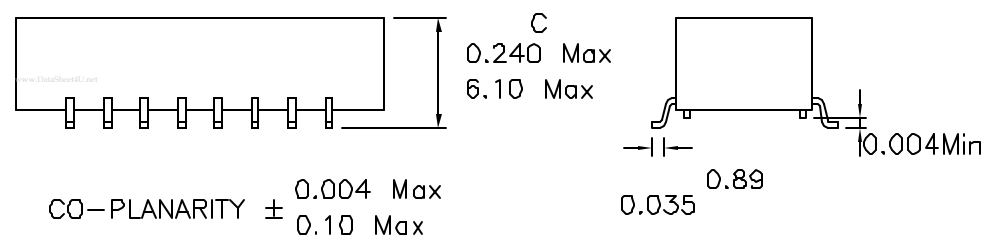
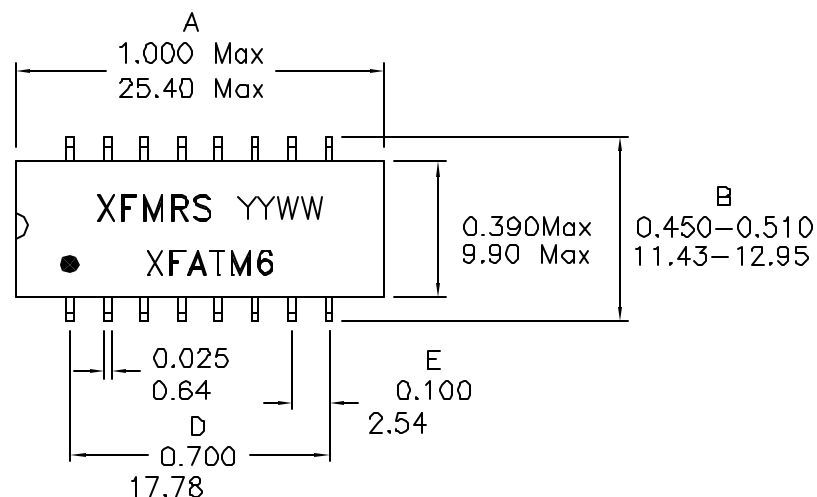
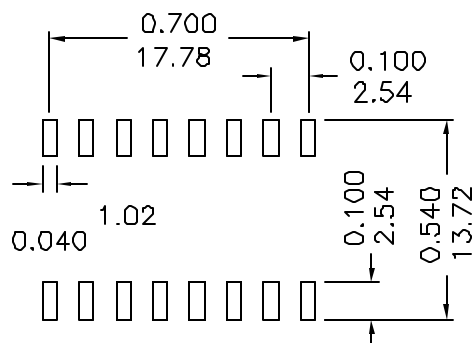


1. Mechanical Dimensions:



CO-PLANARITY ± 0.004 Max
0.10 Max

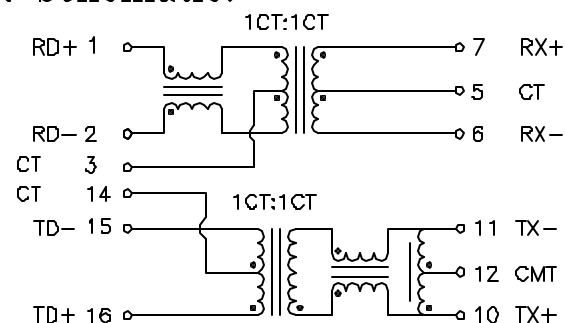


SUGGESTED FOOTPRINT

Notes:

1. Solderability: Leads shall meet MIL-STD-202, Method 208D for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C, UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: ± 0.004 " (0.102mm)
9. Moisture Sensitivity: Level 3
10. Electrical and mechanical specifications 100% tested
11. RoHS Compliant Component

2. Schematic:



3. Electrical Specifications: @25°C

Isolation Voltage: 1500 Vrms

CHIP SIDE OCL: 350uH Min @100KHz 0.1V 8mA

Rise Time (10-90%): 4.0ns Typ

Insertion Loss (100KHz-100MHz): -1.0dB Max

Return Loss: 1-30MHz 40MHz 50MHz 60MHz-80MHz
-20dB -20dB -18dB -14dB (Min)

CMRR: 30MHz 60MHz 100MHz
-42dB -36dB -33dB (Min)

CROSSTALK: 30MHz 60MHz 100MHz
-50dB -40dB -40dB (Min)

XFMRS Inc.
www.XFMRS.com

Title:
HIGH SPEED LAN MAGNETICS

UNLESS OTHERWISE SPECIFIED
TOLERANCES:
.xxx ± 0.010 Inch
Dimensions in Inch/mm
SCALE 2:1 SHT 1 OF 1

P/N: XFATM6		REV. F
DWN.	罗振江	Aug-15-05
CHK.	廖玉坤	Aug-15-05
APP.	BW	Aug-15-05

PROPRIETARY

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